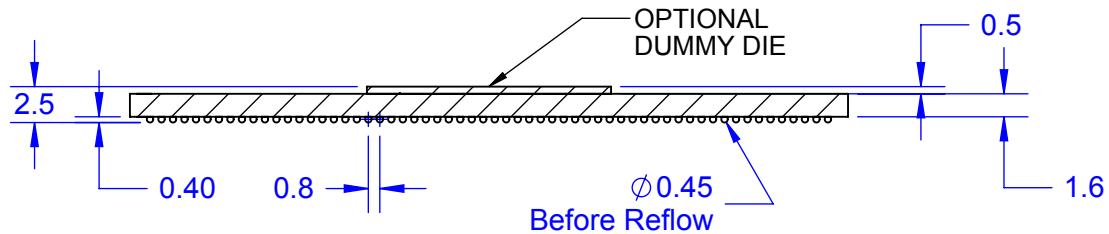
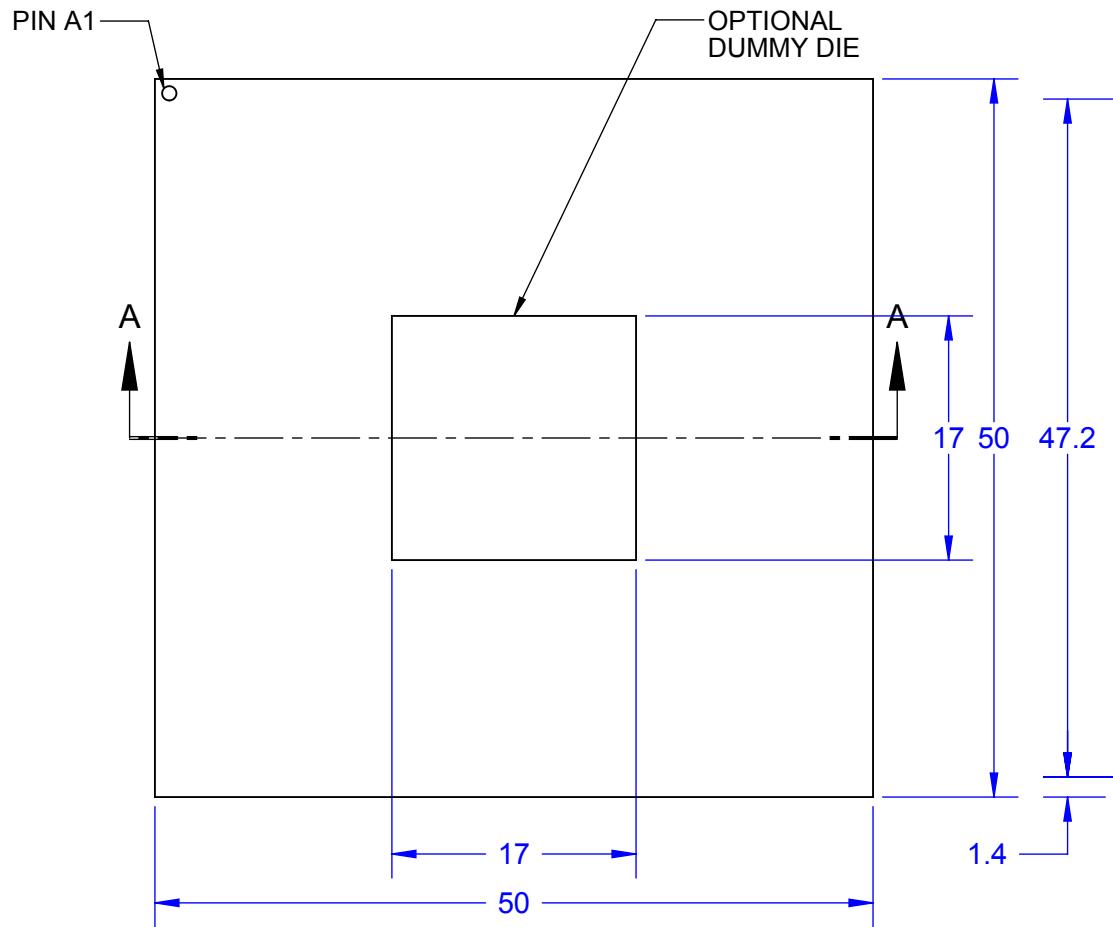


TOP VIEW

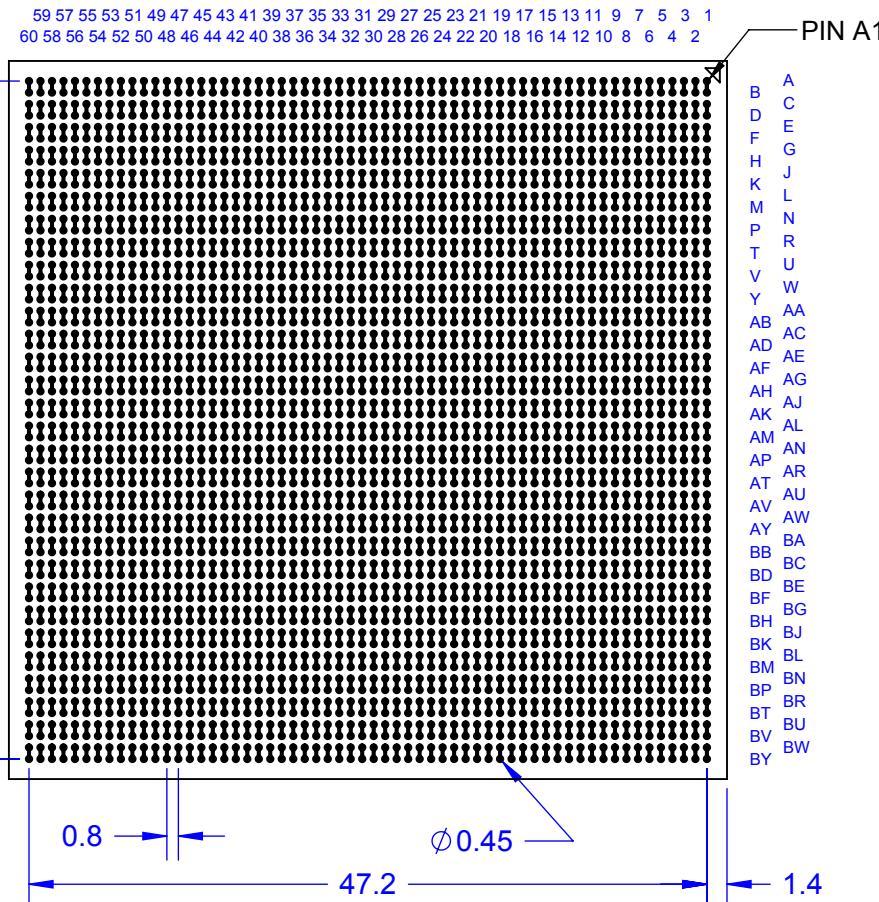


SECTION A-A

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA3600T.8C-DC609	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA3600T.8C-DC609D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA3600T.8-DC609	Sn63/Pb37	NO	NO	NO
LBGA3600T.8-DC609D	Sn63/Pb37	NO	NO	YES

BALL VIEW

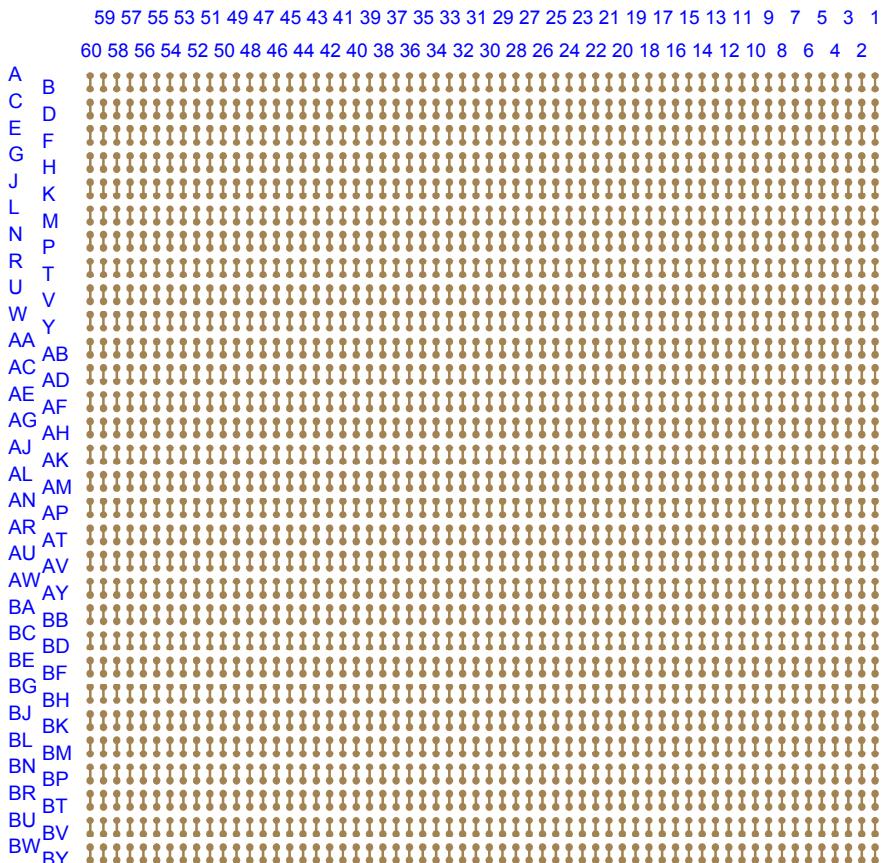


Notes: (Unless Otherwise Specified).

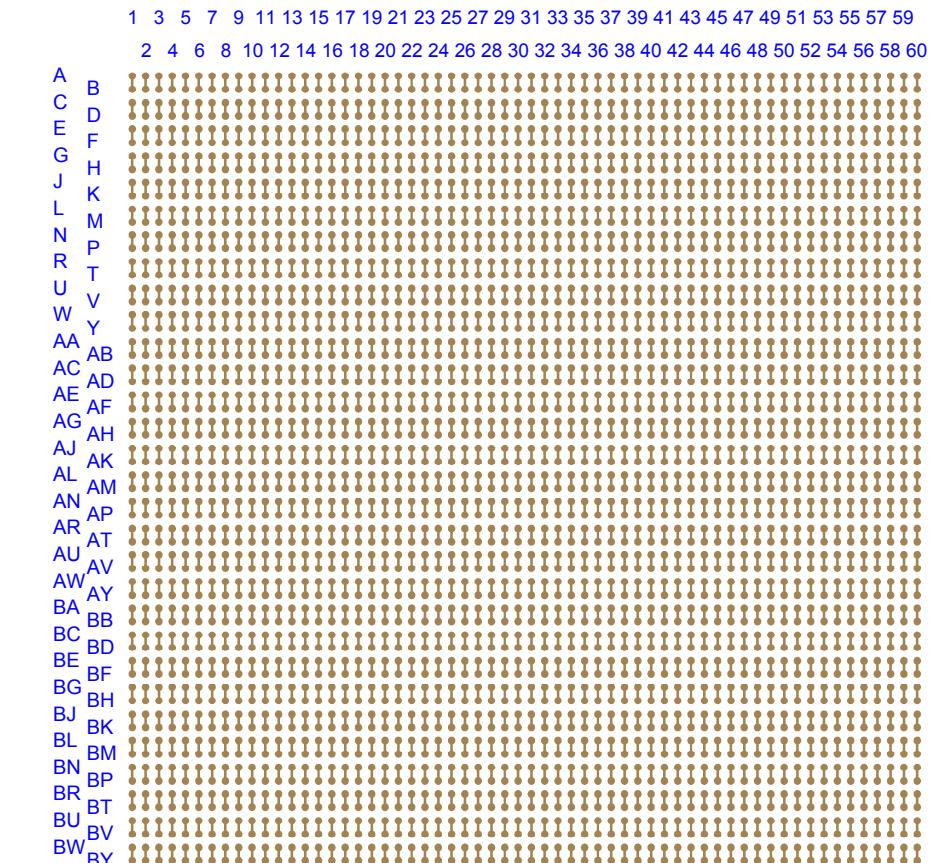
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm (18 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.356mm (14 MIL).
- 5) PAD Cu DIAMETER: 0.508mm (20 MIL).
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT or Polyimide).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

APPROVALS	DATE	TopLine®				
DRAWN	T.Au	10/23/13				
ENG	M. Hart	10/23/13	TITLE LBGA3600T.8C-DC609 DAISY CHAIN DUMMY			
MFG						
QA		SCALE	1.8:1	SIZE	DRAWING NO.	
CUST				A	586091	
REVISED		DO NOT SCALE DRAWING				
		SHEET 1 OF 3				

BALL VIEW



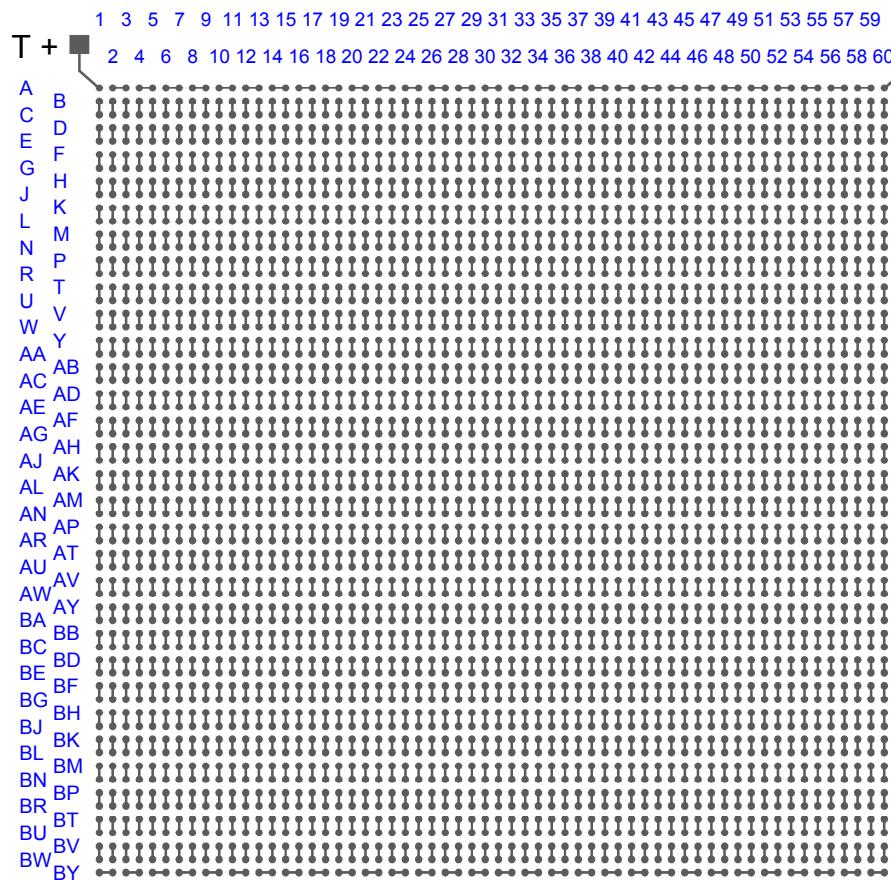
BOTTOM SIDE (TOP X-RAY VIEW)



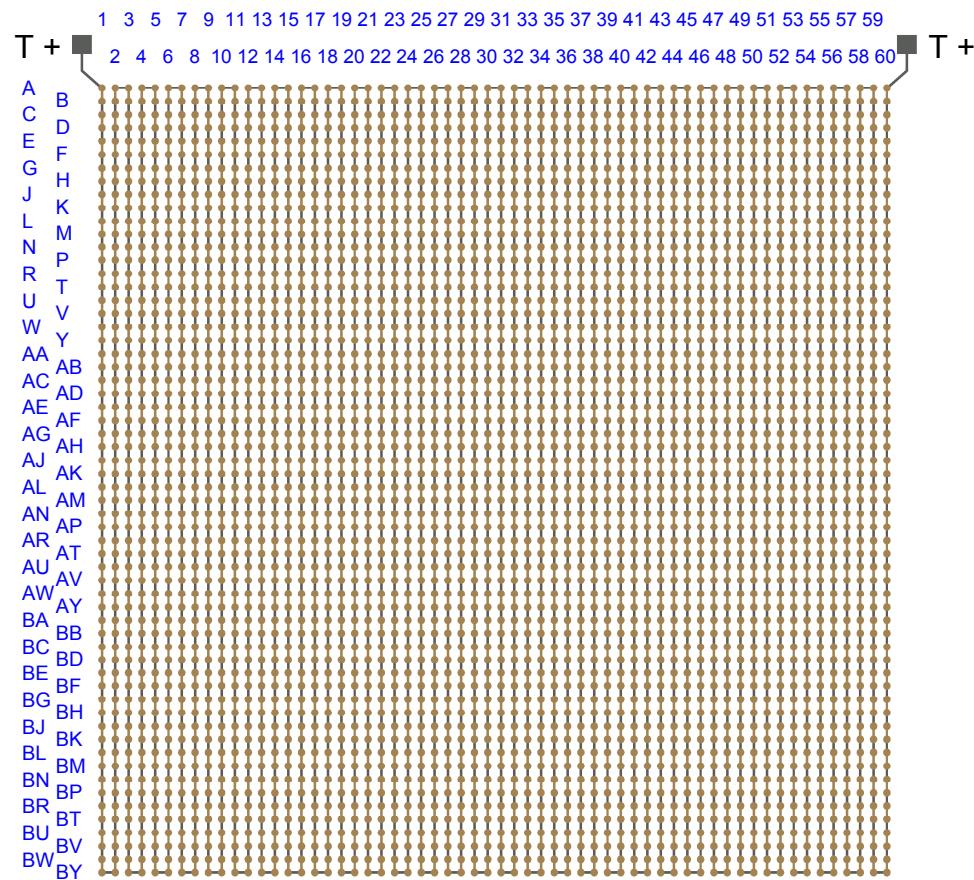
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm (20 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.356mm (14 MIL).

TopLine®			
TITLE	LBGA3600T.8C-DC609 DAISY CHAIN DUMMY		
SCALE	SIZE	DRAWING NO.	REV
1.4:1	A	586091	A
DO NOT SCALE DRAWING			SHEET 2 OF 3



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.508mm (20 MIL).
 - 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
 - 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.356mm (14 MIL).

